

THC63LVD1027

Dual Link LVDS Repeater

General Description

The THC63LVD1027 LVDS(Low Voltage Differential Signaling) repeater is designed to support pixel data transmission between Host and Flat Panel Display up to WUXGA resolution.

THC63LVD1027 receives the dual link LVDS data streams and transmits the LVDS data through various line rate conversion modes, Dual Link Input / Dual Link Output, Single Link Input / Dual Link Output, and Dual Link Input / Single Link Output.

Features

- 30bits/pixel dual link LVDS Receiver
- 30bits/pixel dual Link LVDS Transmitter
- Operating Temperature Range : -40°C~85°C
- Wide LVDS input skew margin: $\pm 480\text{ps}$ at 75MHz
- Accurate LVDS output timing: $\pm 250\text{ps}$ at 75MHz
- Reduced swing LVDS output mode supported to suppress the system EMI
- Various line rate conversion modes supported
 Dual link input / Dual link output [clkout=1x clkin]
 Single link input / Dual link output [clkout=1/2x clkin]
 Dual link input / Single link output [clkout=2x clkin]
- Distribution (signal duplication) mode supported
- Power down mode supported
- 3.3V single voltage power supply
- No external components required for PLLs
- 64pin TSSOP with Exposed PAD (0.5mm lead pitch)

Block Diagram

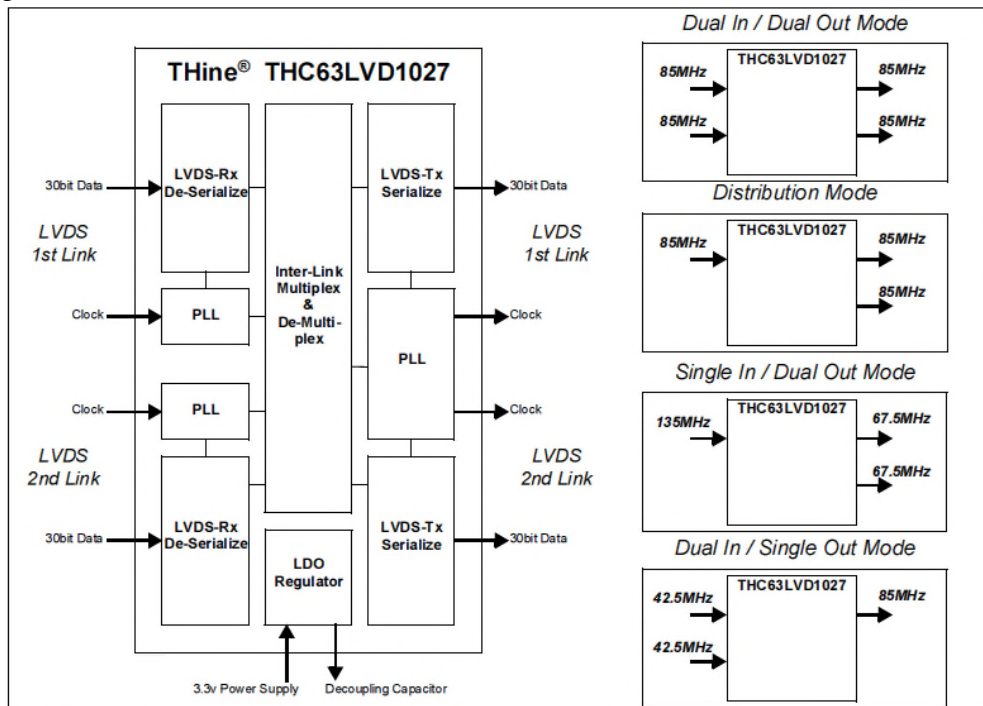


Figure 1. Block Diagram

Pin Diagram

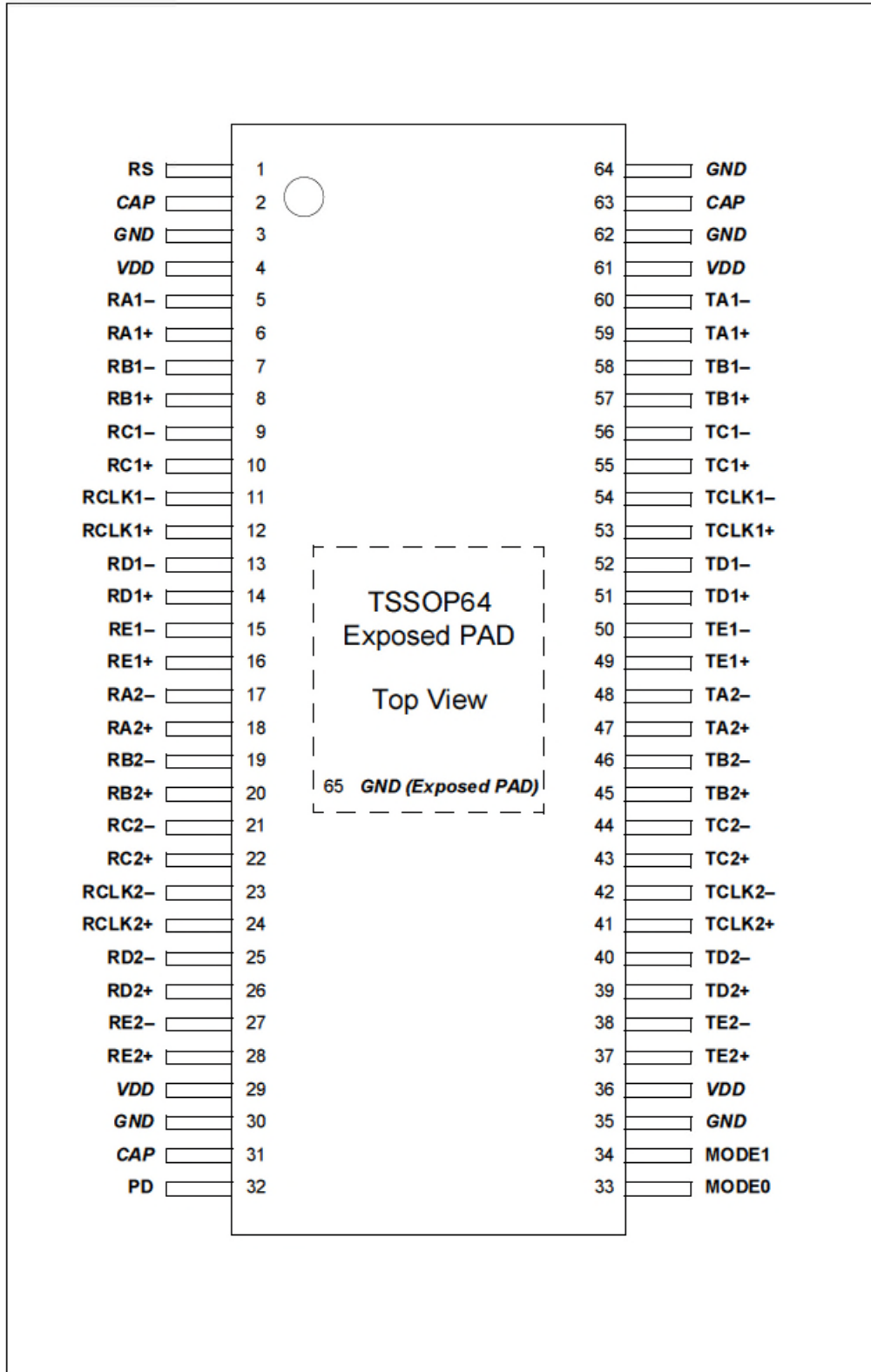


Figure 2. Pin Diagram

Pin Description

Table 1. Pin Description

Pin Name	Direction	Type	Description																								
RA1+/-	Input	LVDS	LVDS data input for channel A of 1st Link																								
RB1+/-			LVDS data input for channel B of 1st Link																								
RC1+/-			LVDS data input for channel C of 1st Link																								
RD1+/-			LVDS data input for channel D of 1st Link																								
RE1+/-			LVDS data input for channel E of 1st Link																								
RCLK1+/-			LVDS clock input for 1st Link																								
RA2+/-			LVDS data input for channel A of 2nd Link																								
RB2+/-			LVDS data input for channel B of 2nd Link																								
RC2+/-			LVDS data input for channel C of 2nd Link																								
RD2+/-			LVDS data input for channel D of 2nd Link																								
RE2+/-			LVDS data input for channel E of 2nd Link																								
RCLK2+/-			LVDS clock input for 2nd Link In Distribution and Single-in/Dual-out mode,RCLK2+/- must be Hi-Z. (See “Mode selection” below in this page.)																								
TA1+/-			Output	LVDS	LVDS data output for channel A of 1st Link																						
TB1+/-					LVDS data output for channel B of 1st Link																						
TC1+/-	LVDS data output for channel C of 1st Link																										
TD1+/-	LVDS data output for channel D of 1st Link																										
TE1+/-	LVDS data output for channel E of 1st Link																										
TCLK1+/-	LVDS clock output for 1st Link																										
TA2+/-	LVDS data output for channel A of 2nd Link																										
TB2+/-	LVDS data output for channel B of 2nd Link																										
TC2+/-	LVDS data output for channel C of 2nd Link																										
TD2+/-	LVDS data output for channel D of 2nd Link																										
TE2+/-	LVDS data output for channel E of 2nd Link																										
TCLK2+/-	LVDS clock output for 2nd Link																										
PD	Input	LV-TTL			Power Down H: Normal operation L: Power down state, all LVDS output signals turn to Hi-Z																						
RS					LVDS output swing level selection H: Normal swing L: Reduced swing																						
MODE1 MODE0			Mode selection																								
			<table border="1"> <thead> <tr> <th>MODE1</th> <th>MODE0</th> <th>RCLK2+/-</th> <th>Description</th> </tr> </thead> <tbody> <tr> <td>L</td> <td>L</td> <td>Clkin</td> <td>Dual-in/Dual-out mode</td> </tr> <tr> <td>L</td> <td>L</td> <td>Hi-Z</td> <td>Distribution mode</td> </tr> <tr> <td>H</td> <td>L</td> <td>Hi-Z</td> <td>Single-in/Dual-out mode</td> </tr> <tr> <td>L</td> <td>H</td> <td>Clkin</td> <td>Dual-in/Single-out mode</td> </tr> <tr> <td>H</td> <td>H</td> <td>-</td> <td>Reserved</td> </tr> </tbody> </table>	MODE1	MODE0	RCLK2+/-	Description	L	L	Clkin	Dual-in/Dual-out mode	L	L	Hi-Z	Distribution mode	H	L	Hi-Z	Single-in/Dual-out mode	L	H	Clkin	Dual-in/Single-out mode	H	H	-	Reserved
MODE1	MODE0	RCLK2+/-	Description																								
L	L	Clkin	Dual-in/Dual-out mode																								
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L	H	Clkin	Dual-in/Single-out mode																								
H	H	-	Reserved																								
VDD	Power	-	3.3V power supply pins																								
GND			Ground pins (Exposed PAD is also Ground)																								
CAP			Decoupling capacitor pins These pins should be connected to external decoupling capacitors(Ccap). Recommended Ccap is 0.1μF.																								

Mode Setting

Table 2. Mode Setting

Input/Output	RCLK2+/-	MODE1 (Input mode)	MODE0 (Output mode)
		H: Single L: Dual	H: Single L: Dual
Dual-In/Dual-Out (Fig.3-1,14-1)	CLK in	L	L
Distribution (Fig.3-2,14-2)	Hi-Z	L	L
Single-In/Dual-Out (Fig.3-3,14-3)	Hi-Z	H	L
Dual-In/Single-Out (Fig.3-4,14-4)	CLK in	L	H
Reserved	-	H	H

Signal Flow for Each Setting

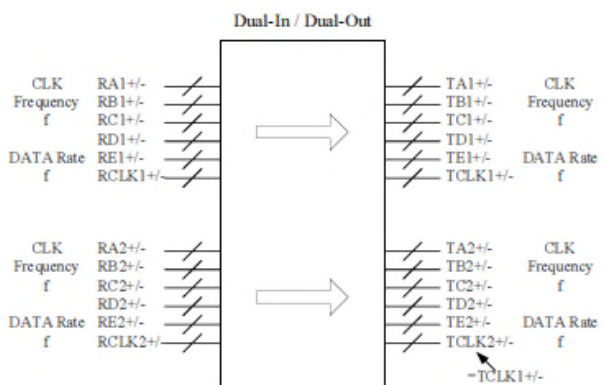


Figure 3-1

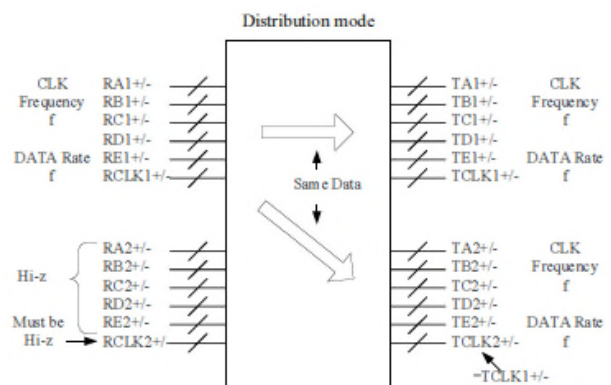


Figure 3-2

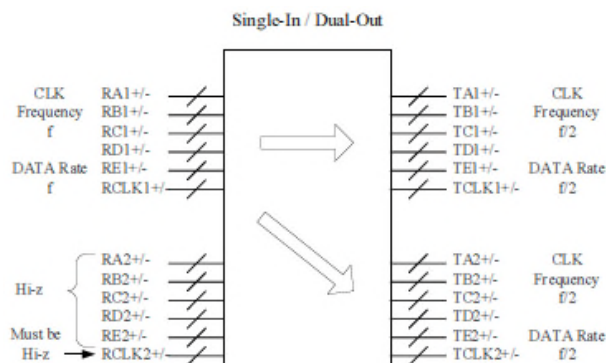


Figure 3-3

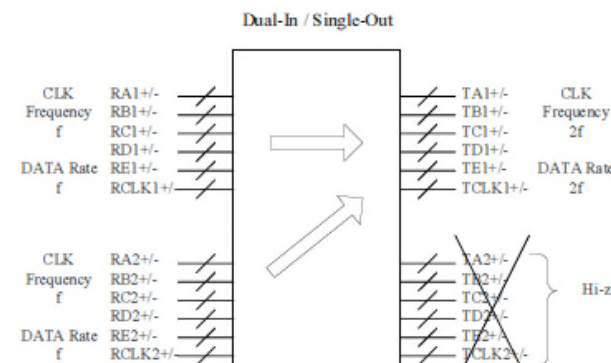


Figure 3-4

Output Control / Fail Safe

THC63LVD1027 has a function to control output depending on LVDS input condition.

Table 3. Output Control

PD	RCLK1+/-	RCLK2+/-	Output
L	*	*	All Hi-Z
H	Hi-Z	*	All Hi-Z
H	CLK in	CLK in	Refer to p.4 Mode Setting #
H	CLK in	Hi-Z	Refer to p.4 Mode Setting #

*: Don't care

#: If a particular input data pair is Hi-Z, the corresponding output data become L according to LVDS DC spec.

For fail-safe purpose, all LVDS input pins are connected to VDD via resistance for detecting Hi-Z state.

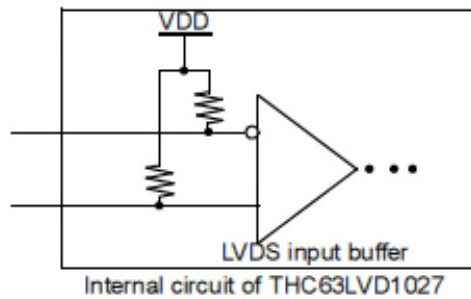


Figure 4. Fail Safe Circuit

Absolute Maximum Ratings

Table 4. Absolute Maximum Rating

Parameter	Min	Max	Unit
Power Supply Voltage	-0.3	+4.0	V
LVC MOS Input Voltage	-0.3	V _{DD} +0.3	V
LVDS Input Voltage	-0.3	V _{DD} +0.3	V
Junction Temperature	-	125	°C
Storage Temperature	-55	125	°C
Reflow Peak Temperature / Time	-	260 / 10sec	°C
Maximum Power Dissipation @+25°C	-	2.5	W

Operating Conditions

Table 5. Operating Condition

Symbol	Parameter	Min	Typ	Max	Unit	
T_a	Operating Ambient Temperature	-40	25	+85	°C	
V_{DD}	Power Supply Voltage	3.0	3.3	3.6	V	
F_{clk}	Dual-In/Dual-Out	Input	20	-	85	MHz
		Output	20	-	85	
	Distribution	Input	20	-	85	MHz
		Output	20	-	85	
	Single-In/Dual-Out	Input	40	-	135	MHz
		Output	20	-	67.5	
	Dual-In/Single-Out	Input	20	-	42.5	MHz
		Output	40	-	85	

Power Consumption

Table 6. Power Consumption

Symbol	Parameter	Conditions			Min	Typ.	Max	Unit
I_{ccw}	Operating Current (Worst Case Pattern) Fig 5.	Dual-In/Dual-Out	CLKIN=40MHz	R_{L,Tx}=100Ω CL=5pF RS=VDD Fig 6.	-	-	265	mA
			CLKIN=65MHz		-	-	305	
			CLKIN=75MHz		-	-	325	
			CLKIN=85MHz		-	-	340	
		Distribution	CLKIN=40MHz		-	-	215	mA
			CLKIN=65MHz		-	-	235	
			CLKIN=75MHz		-	-	245	
			CLKIN=85MHz		-	-	260	
		Single-In/Dual-Out	CLKIN=40MHz		-	-	175	mA
			CLKIN=65MHz		-	-	190	
			CLKIN=75MHz		-	-	200	
			CLKIN=85MHz		-	-	210	
			CLKIN=112MHz		-	-	230	
			CLKIN=135MHz		-	-	250	
		Dual-In/Single-Out	CLKIN=20MHz		-	-	215	mA
			CLKIN=32.5MHz		-	-	235	
CLKIN=37.5MHz	-		-	245				
CLKIN=42.5MHz	-		-	260				
I_{ccs}	Power Down Current	-	-	-	-	8	mA	

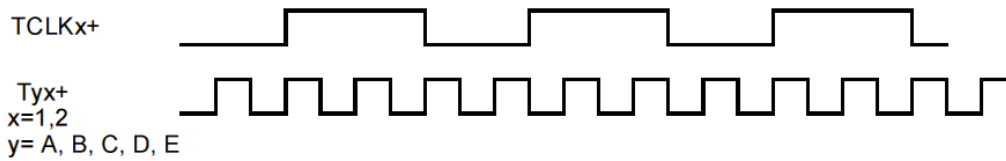


Figure 5. Test Pattern (LVDS Output Full Toggle Pattern)

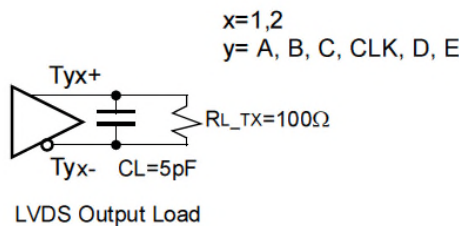


Figure 6. LVDS Output Load

Electrical Characteristics

DC Specifications

Table 7. DC Specifications

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CAP}	Capacitor pin appearance voltage	C _{CAP} =0.1μF	-	1.8	-	V
V _{IL}	LV-TTL Input Low Voltage	-	GND	-	0.8	V
V _{IH}	LV-TTL Input High Voltage	-	2.0	-	VDD	V
I _{IN_TTL}	LV-TTL Input Leakage Current	-	-4	-	+4	μA

LVDS Receiver DC Specifications

Table 8. LVDS Receiver DC Specifications

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{IN_RX}	LVDS-Rx Input Voltage Range	-	0.3	-	2.1	V
V _{IC_RX}	LVDS-Rx Common Voltage	-	0.6	1.2	1.8	
V _{TH_RX}	LVDS-Rx Differential High Threshold	V _{IC_RX} = 1.2V	-	-	+100	mV
V _{TL_RX}	LVDS-Rx Differential Low Threshold		-100	-	-	
V _{ID_RX}	LVDS-Rx Differential Input Voltage	-	100	-	600	
I _{IN_RX}	LVDS-Rx Input Leakage Current	PD=VDD	-0.3	-	+0.3	mA
		PD=GND V _{in} =GND or VDD	-10	-	+10	μA

LVDS Transmitter DC Specifications

Table 9. LVDS Transmitter DC Specifications

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V _{OC_TX}	LVDS-Tx Common Voltage	R _{L_TX} = 100Ω	-	1.125	1.25	1.375	V
ΔV _{OC_TX}	Change in VOC between complementary output states		-	-	-	35	mV
V _{OD_TX}	LVDS-Tx Differential Output Threshold		Normal Swing	250	350	450	mV
			Reduced Swing	100	200	300	
ΔV _{OD_TX}	Change in VOD between complementary output states		-	-	-	35	mV
I _{OS_TX}	LVDS-Tx Output Short Current	V _{DD} =3.3V	V _{out} =GND	-24	-	-	mA
I _{OZ_TX}	LVDS-Tx Output Tri-state Current	PD=GND	V _{out} =GND to VDD	-10	-	+10	μA

AC Specifications

Table 10. AC Specifications

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
t_{LT}	Phase Lock Loop Set Time (Fig 7.)	-	-	-	-	10	ms
t_{DL}	Data Latency (Fig 8.)	Dual-In/Dual-Out	CLKIN=75MHz	$9t_{RCP}+3$	$9t_{RCP}+5$	$9t_{RCP}+7$	ns
		Distribution	CLKIN=75MHz	$9t_{RCP}+3$	$9t_{RCP}+5$	$9t_{RCP}+7$	
		Single-In/Dual-Out	CLKIN=75MHz	$(11+2/7)t_{RCP}+3$	$(11+2/7)t_{RCP}+5$	$(11+2/7)t_{RCP}+7$	
		Dual-In/Single-Out	CLKIN=37.5MHz	$(8+5/14)t_{RCP}+3$	$(8+5/14)t_{RCP}+5$	$(8+5/14)t_{RCP}+7$	
t_{DEH}	DE Input High Time (Fig 9.)	Single-In/Dual-Out	-	$2t_{RCP}$	-	-	ns
t_{DEL}	DE Input Low Time (Fig 9.)		-	$2t_{RCP}$	-	-	
t_{DEINT}	DE Input Period (Fig 9.)		-	$4t_{RCP}$	Must be $2n t_{RCP}$ (n=integer)	-	

AC Timing Diagrams

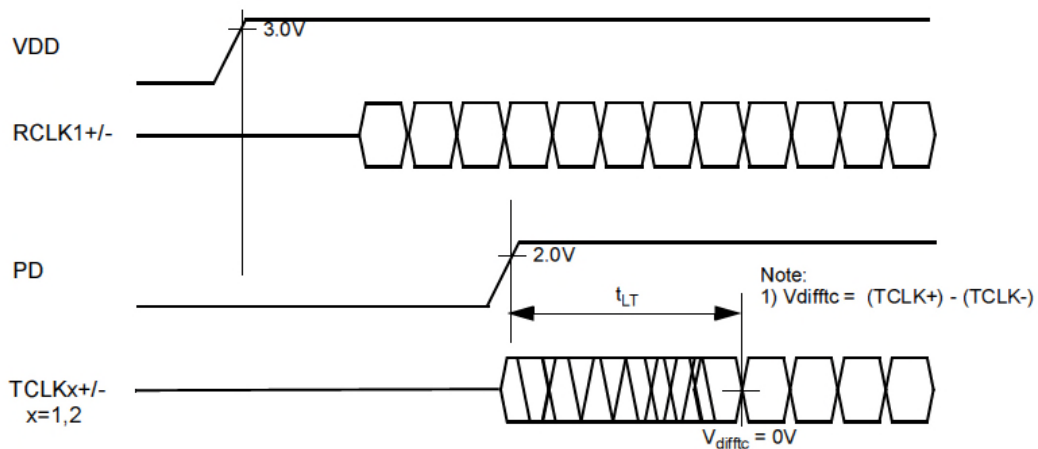


Figure 7. Phase Lock Loop Set Time

AC Timing Diagrams (Continued)

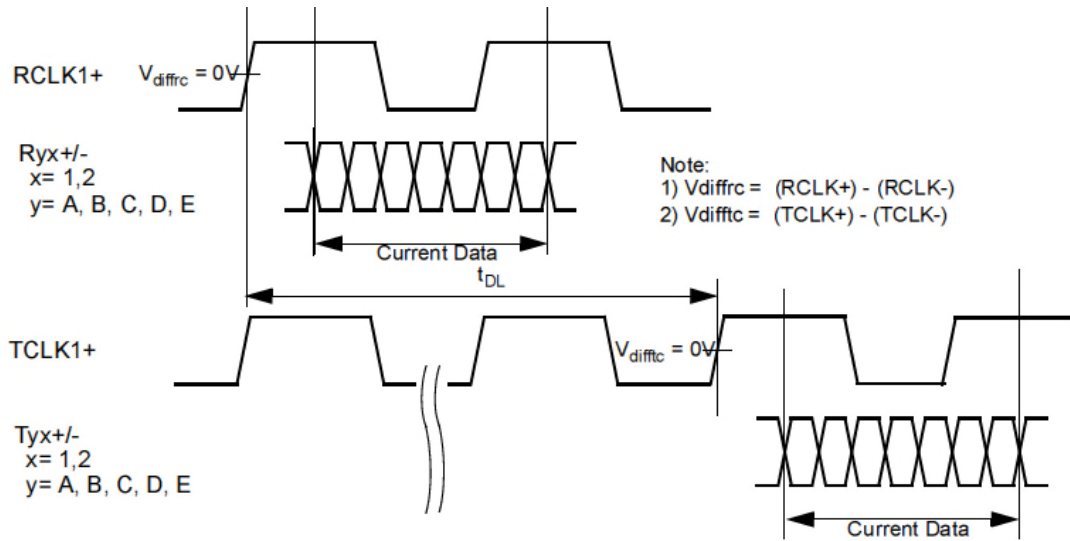


Figure 8. DATA Latency

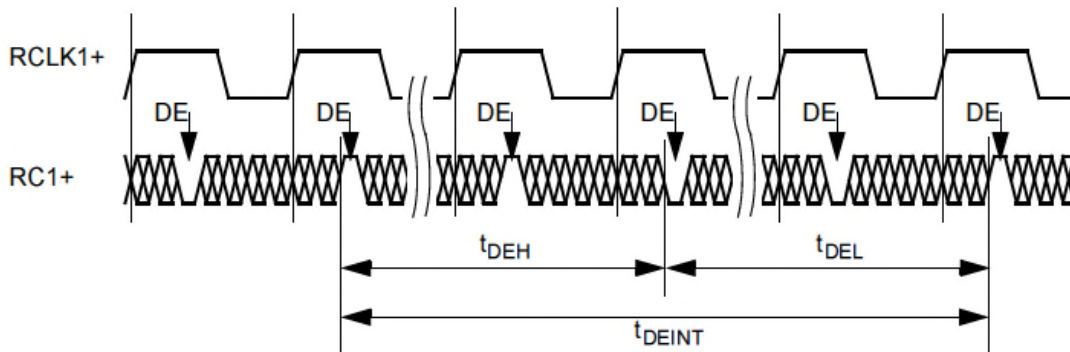


Figure 9. Single Link Input / Dual Link Output Mode RC1(DE) Input Timing

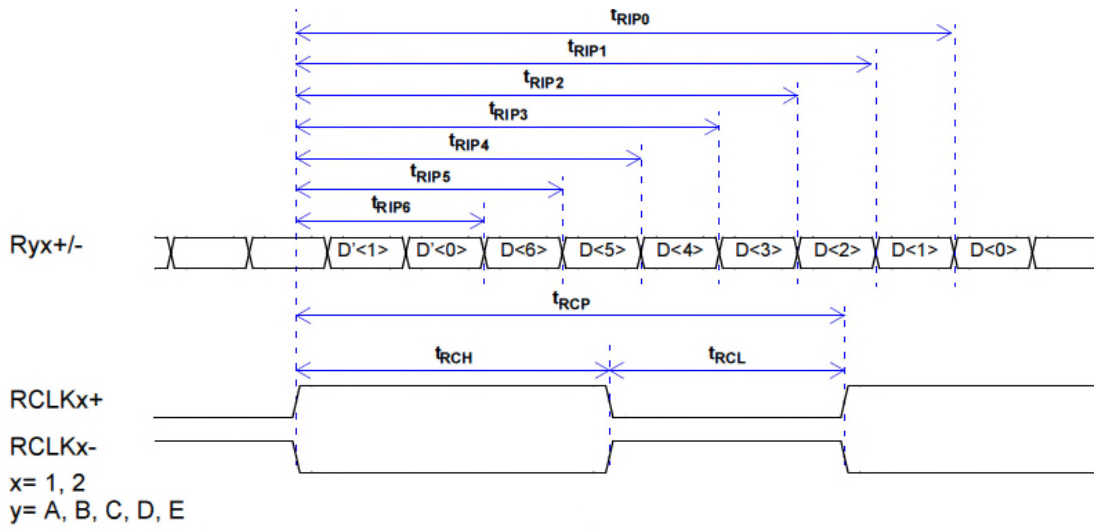
LVDS Receiver AC Specifications

Table 11. LVDS Receiver AC Specifications

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_{RCP}	LVDS Clock Period	-	7.4	-	50	ns
t_{RCH}	LVDS Clock High Duration	-	$2/7t_{RCP}$	$4/7t_{RCP}$	$5/7t_{RCP}$	
t_{RCL}	LVDS Clock Low Duration	-	$2/7t_{RCP}$	$3/7t_{RCP}$	$5/7t_{RCP}$	
t_{RSUP}	LVDS Data Input Setup Margin	CLKIN=75MHz ⁽¹⁾	480	-	-	ps
		CLKIN=112MHz ⁽¹⁾	250	-	-	
		CLKIN=135MHz ⁽¹⁾	220	-	-	
t_{RHLD}	LVDS Data Input Hold Margin	CLKIN=75MHz ⁽¹⁾	480	-	-	ps
		CLKIN=112MHz ⁽¹⁾	250	-	-	
		CLKIN=135MHz ⁽¹⁾	220	-	-	
t_{RIP6}	LVDS Data Input Position 6	-	$2/7t_{RCP}-t_{RHLD}$	$2/7t_{RCP}$	$2/7t_{RCP}+t_{RSUP}$	ps
t_{RIP5}	LVDS Data Input Position 5	-	$3/7t_{RCP}-t_{RHLD}$	$3/7t_{RCP}$	$3/7t_{RCP}+t_{RSUP}$	
t_{RIP4}	LVDS Data Input Position 4	-	$4/7t_{RCP}-t_{RHLD}$	$4/7t_{RCP}$	$4/7t_{RCP}+t_{RSUP}$	
t_{RIP3}	LVDS Data Input Position 3	-	$5/7t_{RCP}-t_{RHLD}$	$5/7t_{RCP}$	$5/7t_{RCP}+t_{RSUP}$	
t_{RIP2}	LVDS Data Input Position 2	-	$6/7t_{RCP}-t_{RHLD}$	$6/7t_{RCP}$	$6/7t_{RCP}+t_{RSUP}$	
t_{RIP1}	LVDS Data Input Position 1	-	$7/7t_{RCP}-t_{RHLD}$	$7/7t_{RCP}$	$7/7t_{RCP}+t_{RSUP}$	
t_{RIP0}	LVDS Data Input Position 0	-	$8/7t_{RCP}-t_{RHLD}$	$8/7t_{RCP}$	$8/7t_{RCP}+t_{RSUP}$	
t_{CK12}	Skew Time Between RCLK1 and RCLK2	-	-0.3 t_{RCP}	-	+0.3 t_{RCP}	ps

(1) $V_{IC_RX}=1.2V$, $t_{RCH}=4/7 t_{RCP}$

LVDS Receiver Input Timing



Ry1+/- skew margin is the one between RCLK1+/- and Ry1+/-.
Ry2+/- skew margin is the one between RCLK2+/- and Ry2+/-.

Figure 10. LVDS Receiver Timing

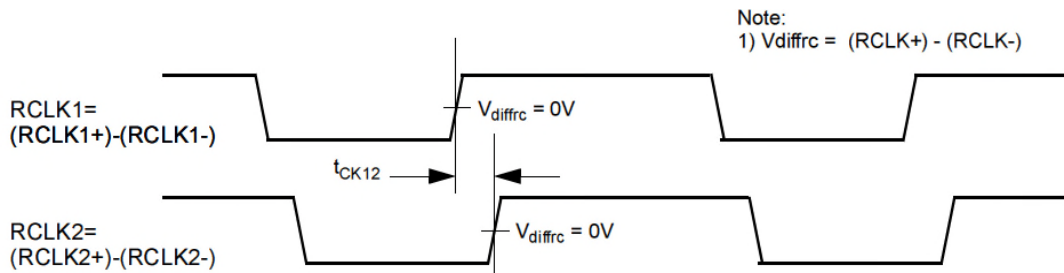


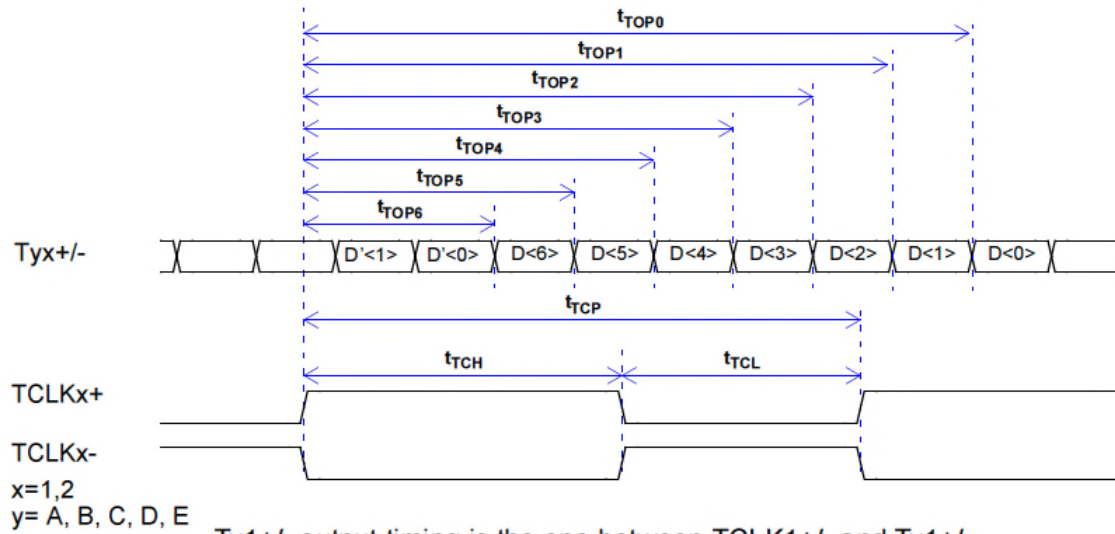
Figure 11. Skew time between RCLK1 and RCLK2

LVDS Transmitter AC Specifications

Table 12. LVDS Transmitter AC Specifications

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_{TCP}	LVDS Clock Period	-	11.76	-	50	ns
t_{TCH}	LVDS Clock High Duration	-	-	$4/7t_{TCP}$	-	
t_{TCL}	LVDS Clock Low Duration	-	-	$3/7t_{TCP}$	-	
t_{TSUP}	LVDS Data Output Setup	CLKOUT=75MHz	-	-	250	ps
t_{THLD}	LVDS Data Output Hold	CLKOUT=75MHz	-	-	250	ps
t_{TOP6}	LVDS Data Output Position 6	-	$2/7t_{TCP}-t_{THLD}$	$2/7t_{TCP}$	$2/7t_{TCP}+t_{TSUP}$	ps
t_{TOP5}	LVDS Data Output Position 5	-	$3/7t_{TCP}-t_{THLD}$	$3/7t_{TCP}$	$3/7t_{TCP}+t_{TSUP}$	
t_{TOP4}	LVDS Data Output Position 4	-	$4/7t_{TCP}-t_{THLD}$	$4/7t_{TCP}$	$4/7t_{TCP}+t_{TSUP}$	
t_{TOP3}	LVDS Data Output Position 3	-	$5/7t_{TCP}-t_{THLD}$	$5/7t_{TCP}$	$5/7t_{TCP}+t_{TSUP}$	
t_{TOP2}	LVDS Data Output Position 2	-	$6/7t_{TCP}-t_{THLD}$	$6/7t_{TCP}$	$6/7t_{TCP}+t_{TSUP}$	
t_{TOP1}	LVDS Data Output Position 1	-	$7/7t_{TCP}-t_{THLD}$	$7/7t_{TCP}$	$7/7t_{TCP}+t_{TSUP}$	
t_{TOP0}	LVDS Data Output Position 0	-	$8/7t_{TCP}-t_{THLD}$	$8/7t_{TCP}$	$8/7t_{TCP}+t_{TSUP}$	
t_{LVT}	LVDS Transition Time (Fig 13.)	Fig.6	-	0.6	1.5	ns

LVDS Transmitter Output Diagram



$Ty_{1+/-}$ output timing is the one between $TCLK_{1+/-}$ and $Ty_{1+/-}$.
 $Ty_{2+/-}$ output timing is the one between $TCLK_{2+/-}$ and $Ty_{2+/-}$.

Figure 12. LVDS Transmitter Timing

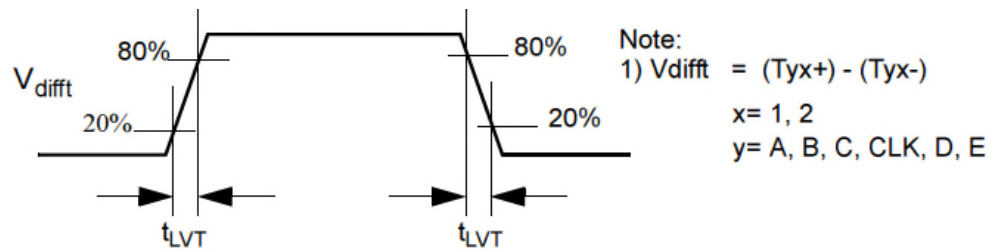
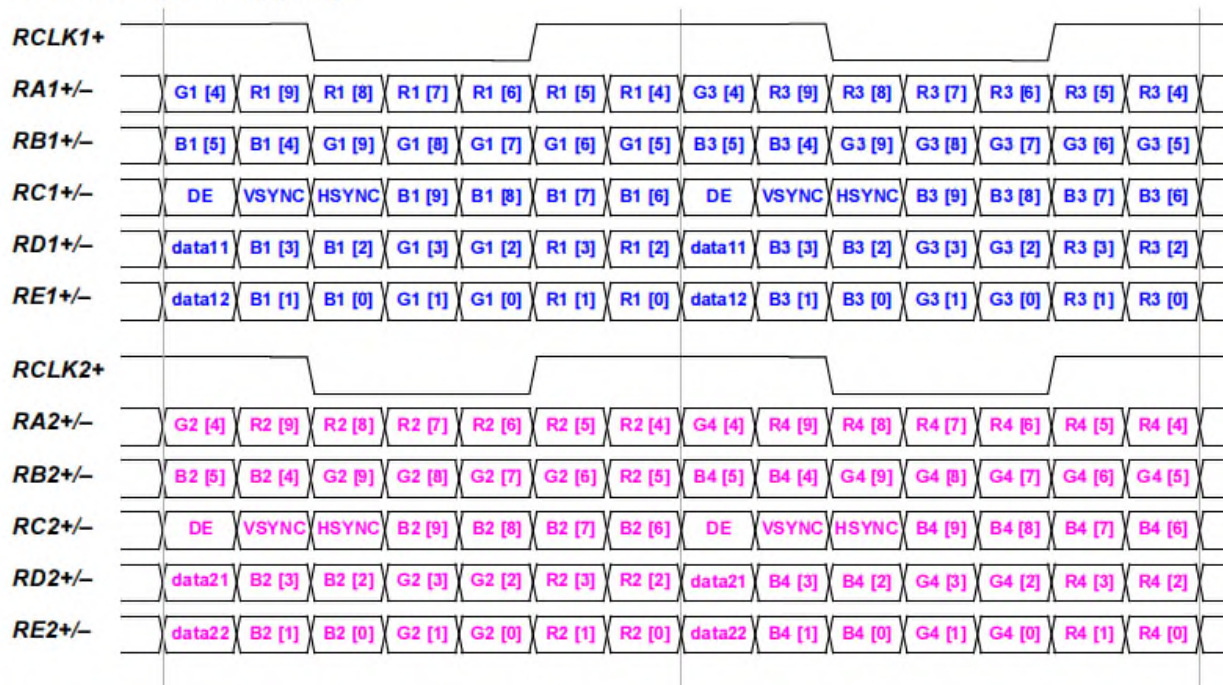


Figure 13. LVDS Transition Timing

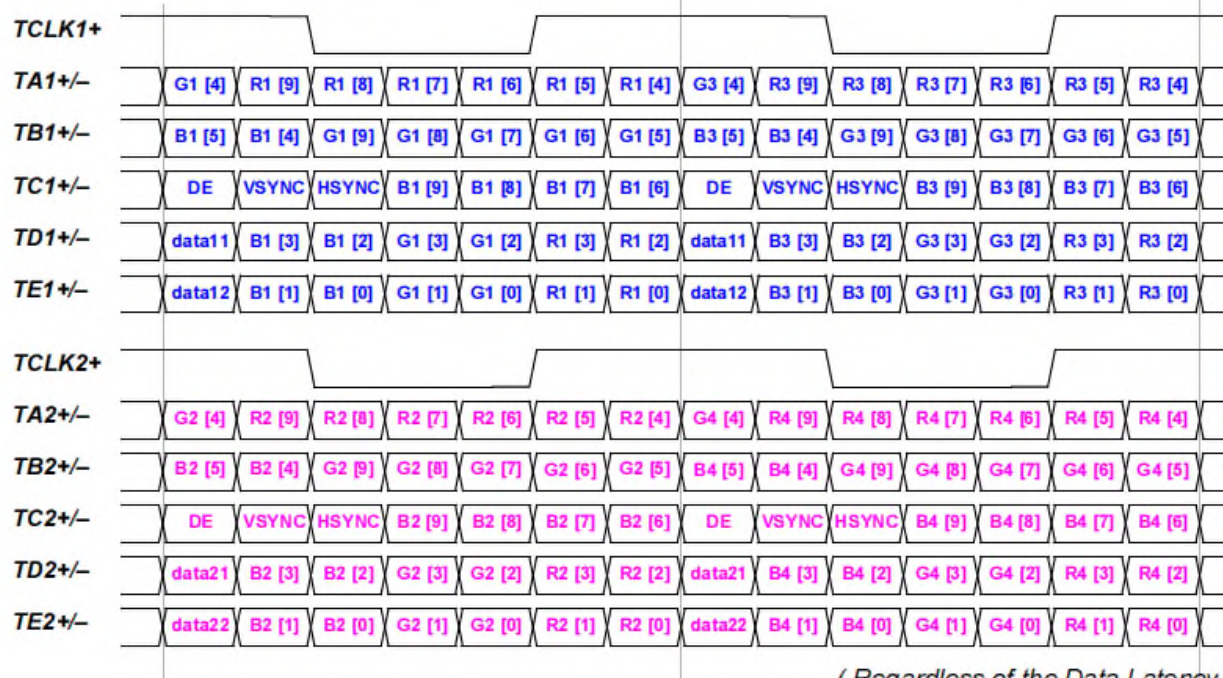
LVDS Data Mapping

Dual-In / Dual-Out

LVDS-Rx Input Mapping



LVDS-Tx Output Mapping



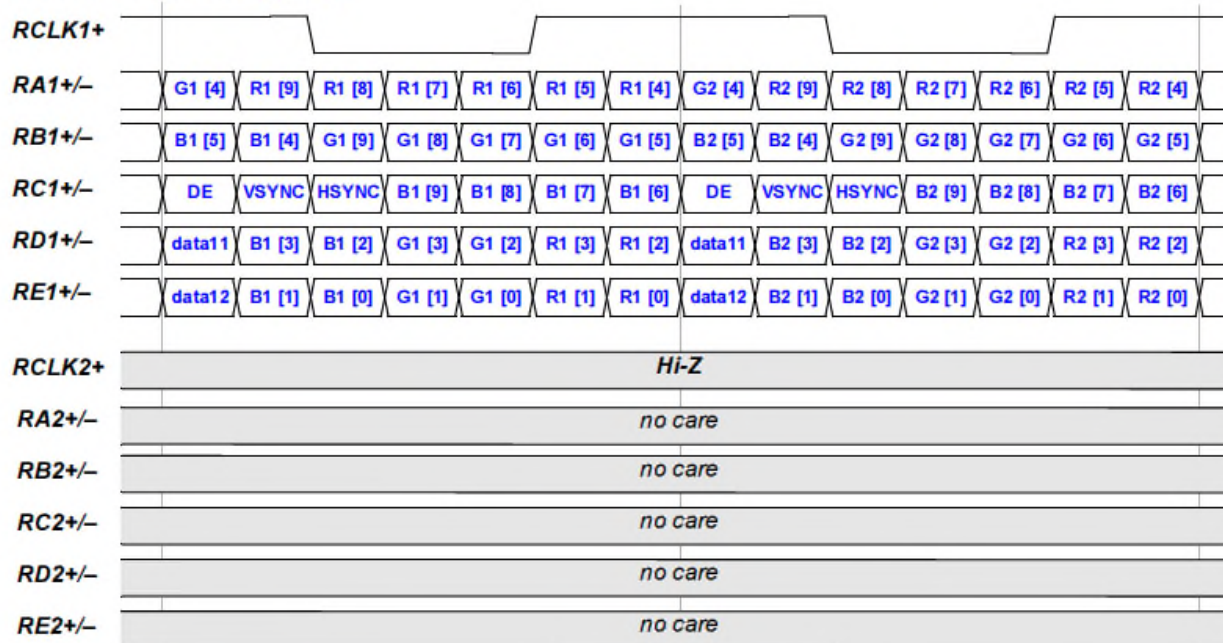
Data bits "data11, data12, data21, data22" are available for additional data transmission.

Figure 14-1. Data Mapping for Dual-In/Dual-Out

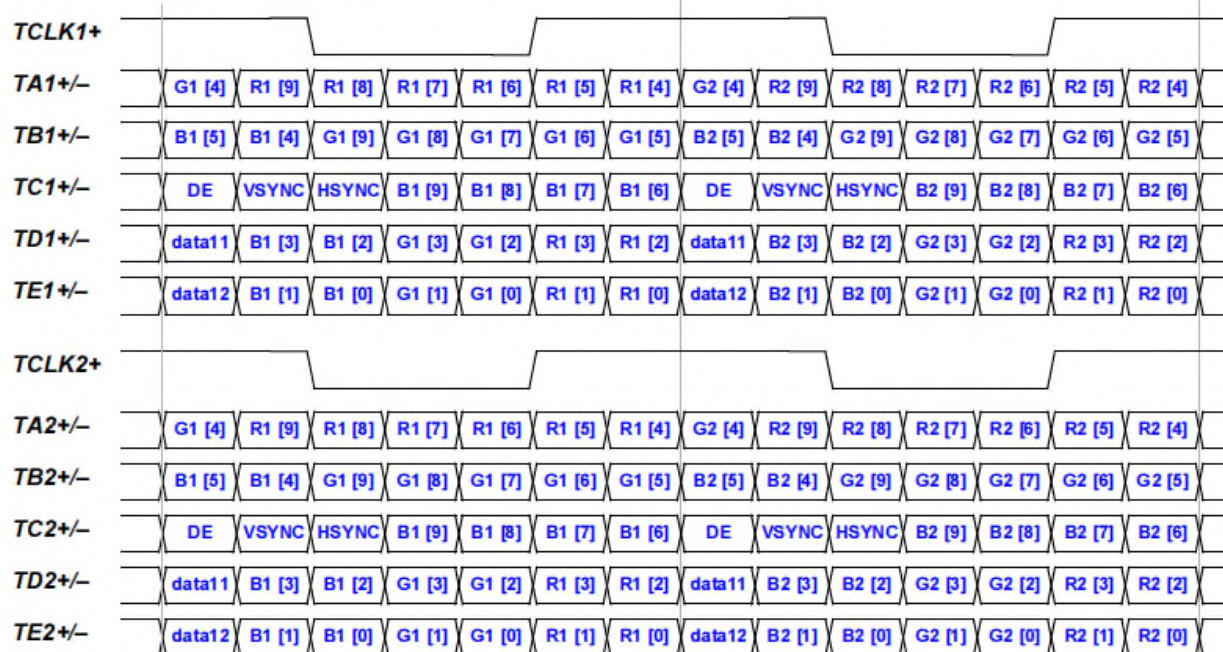
Distribution Mode

In Distribution mode, RCLK2+/- must be Hi-Z.

LVDS-Rx Input Mapping



LVDS-Tx Output Mapping



(Regardless of the Data Latency)

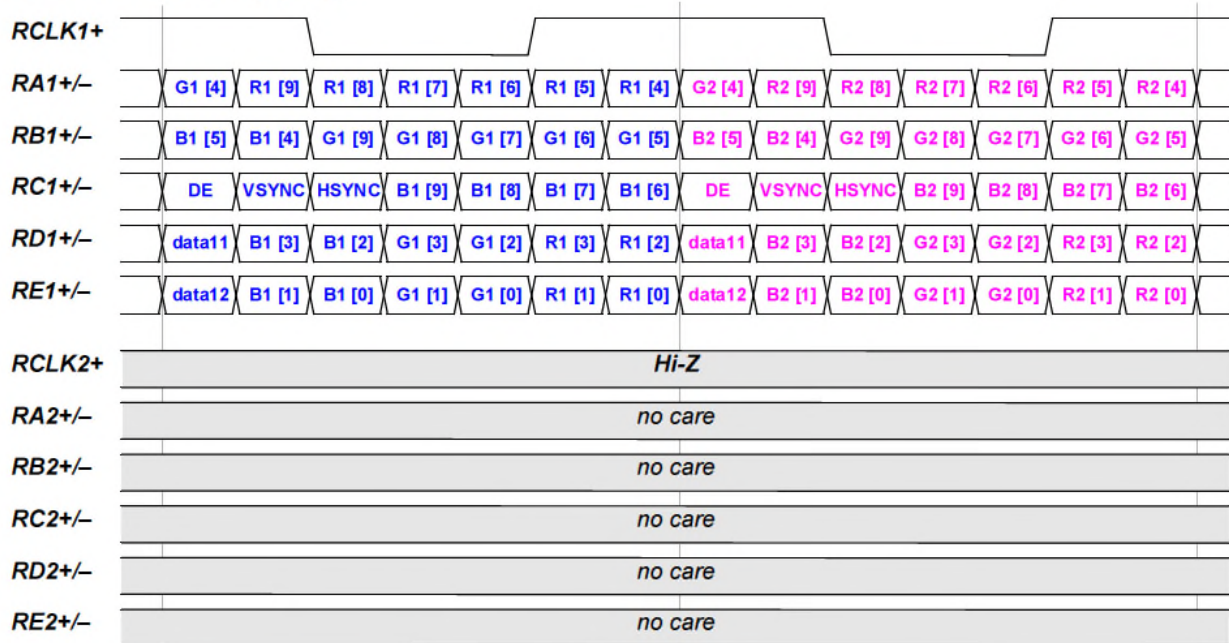
Data bits "data11, data12" are available for additional data transmission.

Figure 14-2. Data Mapping for Distribution mode

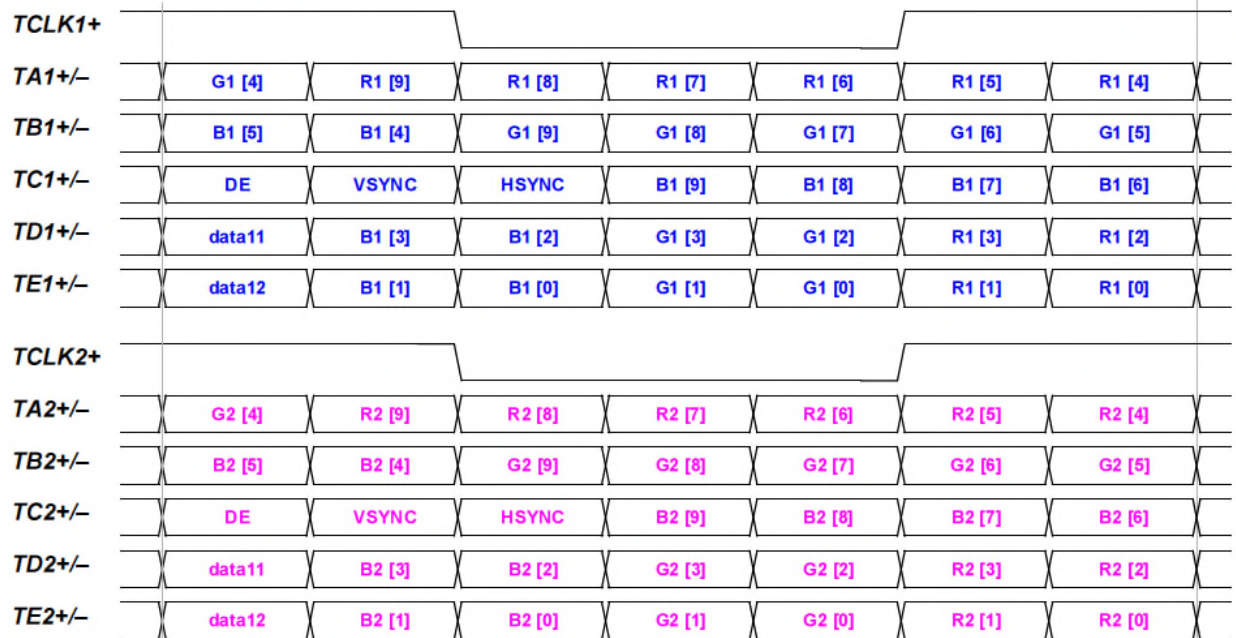
Single-In / Dual-Out

In Single-in / Dual-out mode, RCLK2+/- must be Hi-Z.

LVDS-Rx Input Mapping



LVDS-Tx Output Mapping

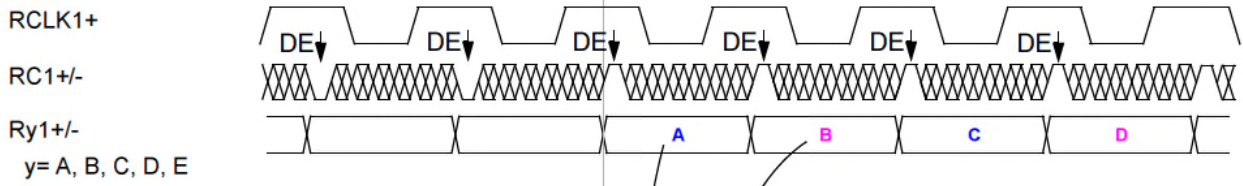


(Regardless of the Data Latency)

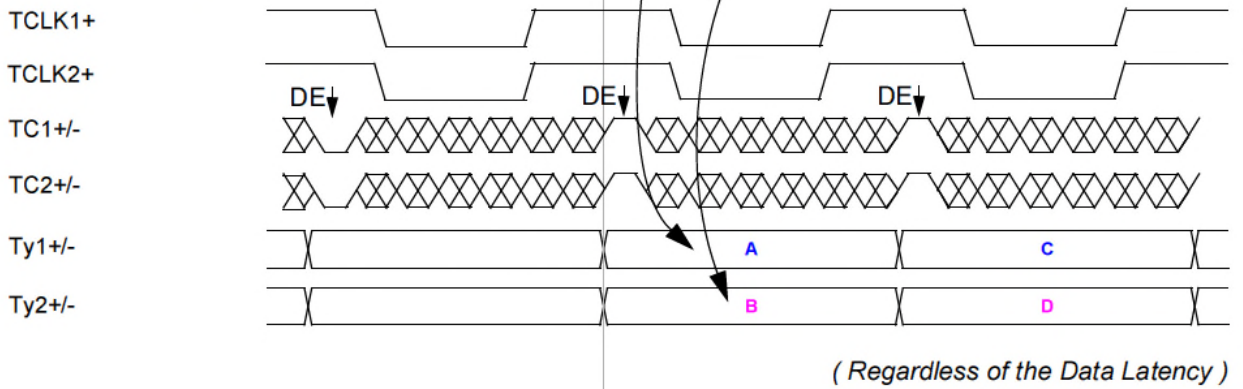
Data bits "data11, data12" are available for additional data transmission.

Figure 14-3(a). Data Mapping for Single-In/Dual-Out

Single Link Input



Dual Link Output



Schematic diagram of DE transition

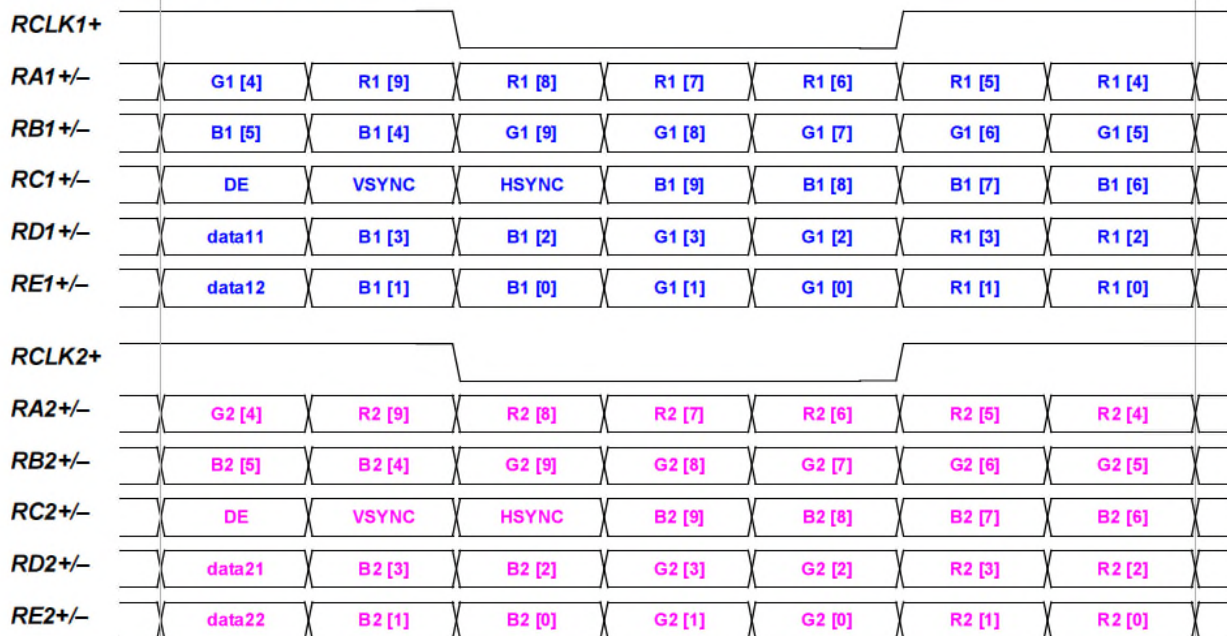


Single-in / Dual-out mode uses DE signal L-to-H-edge to start distribution of input data.

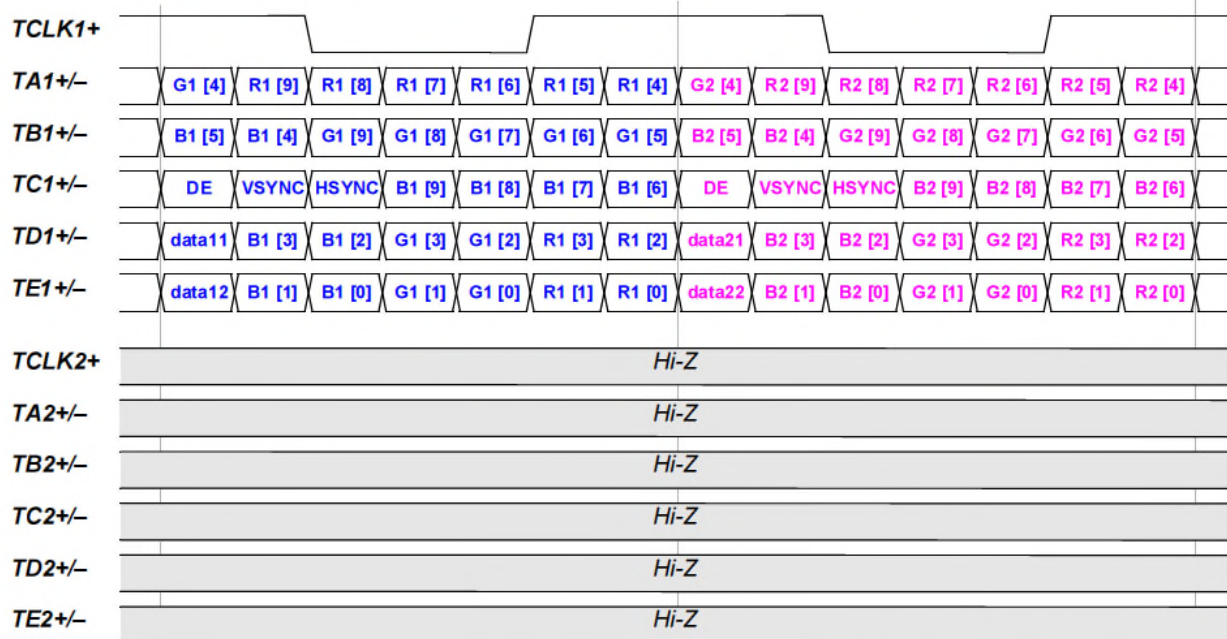
Figure 14-3(b). Data Mapping for Single-In/Dual-Out

Dual-In / Single-Out

LVDS-Rx Input Mapping



LVDS-Tx Output Mapping



(Regardless of the Data Latency)

Data bits "data11, data12, data21, data22" are available for additional data transmission.

Figure 14-4. Data Mapping for Dual-In/Single-Out

Notes

1) LVDS input pin connection

When LVDS line is not derived from the previous device, the line is pulled up to 3.3V internally in THC63LVD1027. This can cause violation of absolute maximum ratings to the previous LVDS Tx device whose operating condition is lower voltage power supply than 3.3V. This phenomenon may happen at power on phase of the whole system including THC63LVD1027. One solution for this problem is PD=L control during no LVDS input period because pull-up resistors are cut off at power down state.

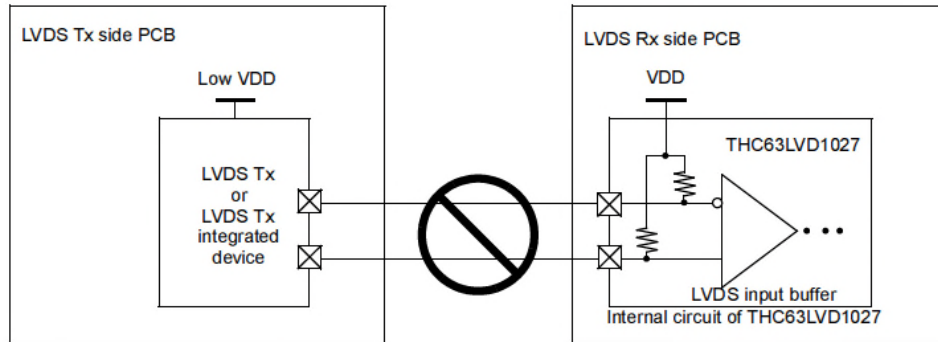


Figure 15. LVDS input pin connection

2) Power On Sequence

Don't input RCLK1+/- and RCLK2+/- before THC63LVD1027 is on in order to keep absolute maximum ratings.

3) Cable Connection and Disconnection

Don't connect and disconnect the LVDS cable, when the power is supplied to the system.

4) GND Connection

Connect the each GND of the PCB which Transmitter, Receiver and THC63LVD1027 on it. It is better for EMI reduction to place GND cable as close to LVDS cable as possible.

5) Multi Drop Connection

Multi drop connection is not recommended.

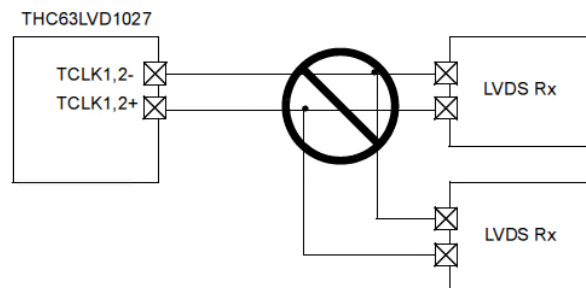


Figure 16. Multi Drop Connection

6) Asynchronous use

Asynchronous use such as following systems are not recommended. Page.11 tCK12 spec should be kept.

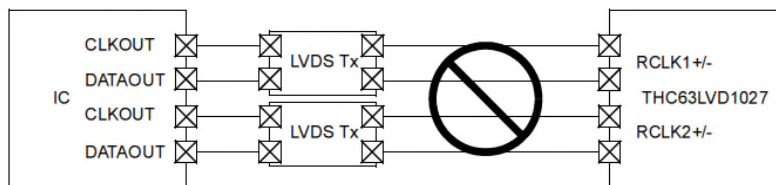


Figure 17-1. Asynchronous Use1

Asynchronous use such as following systems are not recommended.

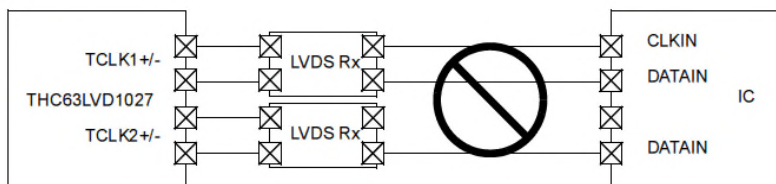
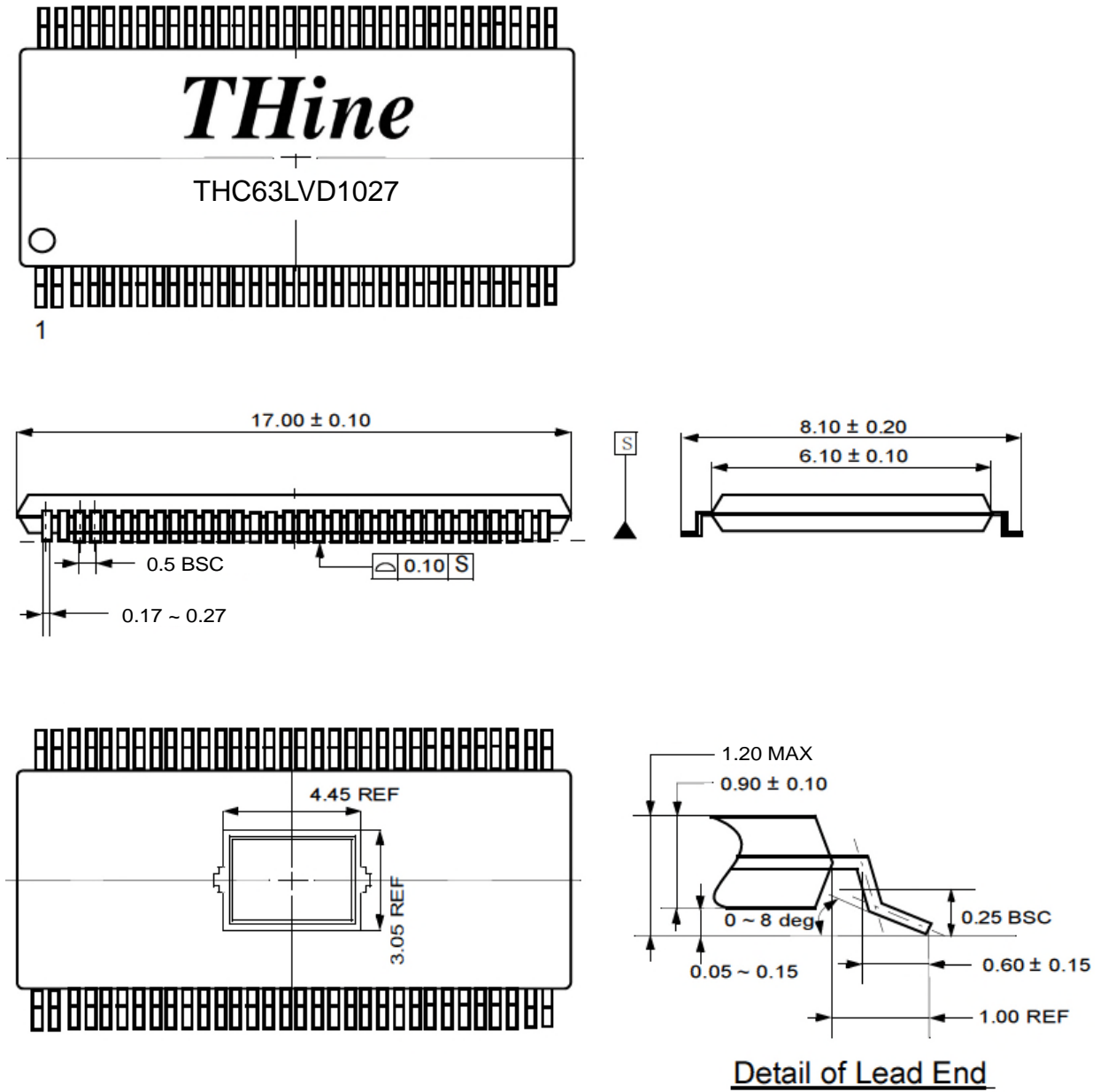


Figure 17-2. Asynchronous Use2

7) De-coupling capacitor

THC63LVD1027 requires appropriate de-coupling capacitor placement on VDD. Especially, VDD pin 36 and pin 61 requires 0.1uF and 4.7nF capacitor parallel placement close to IC pins.

Package



Detail of Lead End

Unit: mm

Exposed PAD is GND and must be soldered to PCB.

Figure 18. Package Diagram

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